DON Number	20100000					7/14/2010			
PCN Number:	20160629004 PCN Date: 7/14/2016					//14/2016			
Title: Datasheet for									
Customer Contact:	PCN Manager		De	ept: Quality Services					
Change Type:						<u></u>			
Assembly Site		Design	$ \square$	Wafer					
Assembly Process		Data Sheet			Bump Material				
Assembly Materials		Part number change	H		Bump Process				
Mechanical Specifi		Test Site			r Fab Site				
Packing/Shipping/		Test Process	H		Vafer Fab Materials				
Notification Dataila									
Description of Chang	Notification Details								
Description of Chang		ouncing an information on	ly pc	tificatio	.				
The product datasheet(The following change h	s) is being upda	ted as summarized below.							
Texas Instruments						LP2982			
 INSTRUMENTS 		SN\	/S128K	-MARCH 20	00-REVI	SED JUNE 2016			
Changes from Revision J (A	pril 2013) to Revision	К				Page			
Deleted TM symbol from VIP - no longer trademarked; changed word in title from "Regulator" to "LDO"									
http://www.ti.com/proc Reason for Change:	<u>1uct/LP2982</u>								
To more accurately refl	ect device chara	cteristics.							
		nction, Quality or Relia	bility	(nosi	tive	/ negative):			
		cation change announceme							
Changes to product identification resulting from this PCN:									
None.									

Product Affected:						
LP2982AIM5-3.3	LP2982AIM5-3.0/NOPB	LP2982AIM5-5.0/NOPB				
LP2982IM5-3.0/NOPB	LP2982AIM5-3.3/NOPB	LP2982AIM5X-3.0/NOPB				
LP2982AIM5-5.0	LP2982AIM5X-3.3/NOPB	LP2982AIM5X-5.0/NOPB				
LP2982IM5-3.3/NOPB	LP2982IM5-5.0/NOPB	LP2982IM5X-3.0/NOPB				
LP2982IM5X-3.3/NOPB	LP2982IM5X-5.0/NOPB					

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com